

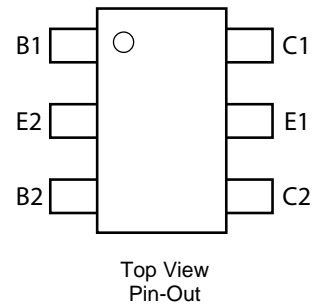
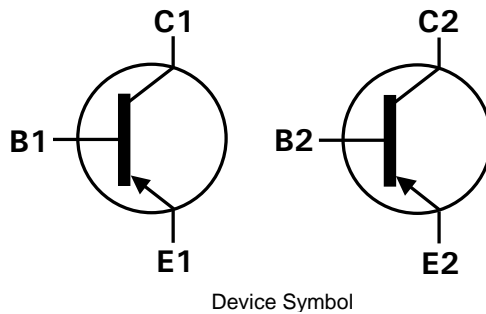
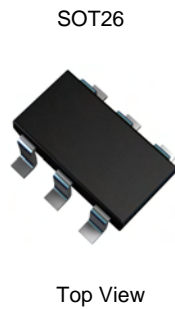
60V DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features & Benefits

- $BV_{CEO} > -60V$
- $I_{CM} = -1A$ Peak Pulse Current
- General purpose NPN transistors ideally suited for low power amplification and switching applications
- Dual transistors in a single SOT26 package taking half the footprint of two equivalent transistors in SOT23
- Epitaxial planar die construction
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating: Matte Tin Finish annealed over Copper leadframe
- Weight: 0.015 grams (approximate)

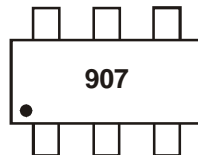


Ordering Information (Note 3)

| Product | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|-------------|---------|--------------------|-----------------|-------------------|
| DMMT2907A-7 | 907 | 7 | 8 | 3,000 |

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>
 3. For packaging details, go to our website at <http://www.diodes.com>

Marking Information



907 = Product Type Marking Code

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

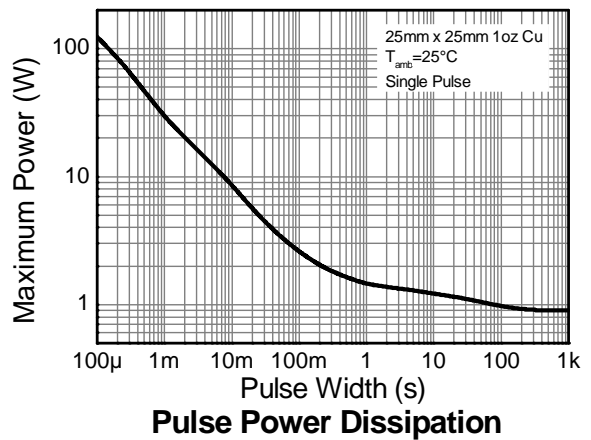
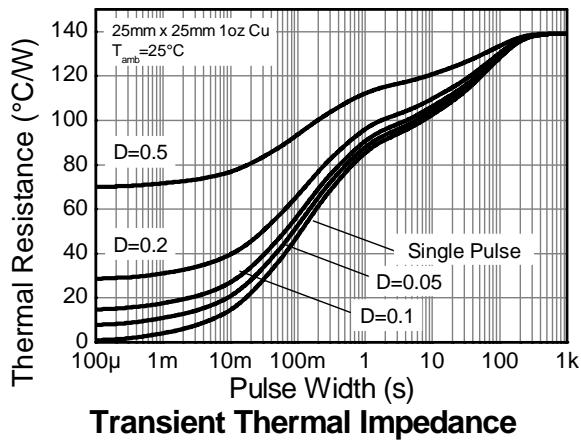
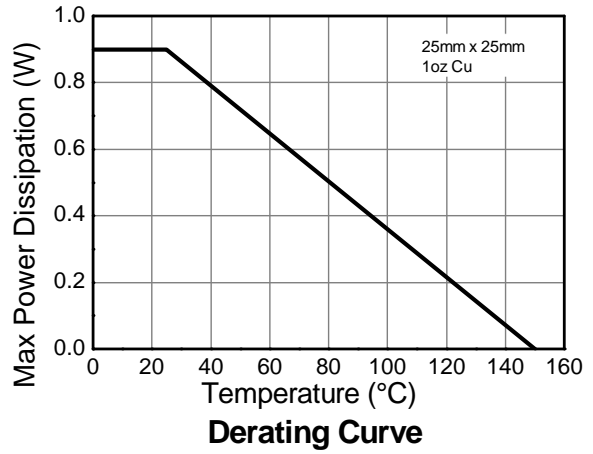
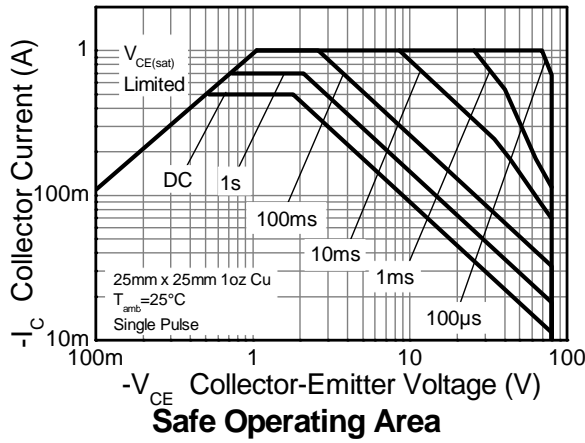
| Characteristic | Symbol | Value | Unit |
|-------------------------------|-----------|-------|------|
| Collector-Base Voltage | V_{CBO} | -60 | V |
| Collector-Emitter Voltage | V_{CEO} | -60 | V |
| Emitter-Base Voltage | V_{EBO} | -5 | V |
| Continuous Collector Current | I_C | -600 | mA |
| Peak Pulsed Collector Current | I_{CM} | -1 | A |

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------------|--------------------|
| Power Dissipation | P_D | 1.28 | W |
| Linear Derating Factor | | 10.3 | |
| | $R_{\theta JA}$ | 0.90 | $^\circ\text{C/W}$ |
| | | 7.14 | |
| Thermal Resistance, Junction to Ambient | $R_{\theta JL}$ | 97 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction to Lead | | 140 | |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

- Notes:
4. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 5. Same as note (4), except the device is measured at $t \leq 5$ sec.
 6. For a dual device with one active die.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).

Thermal Characteristics

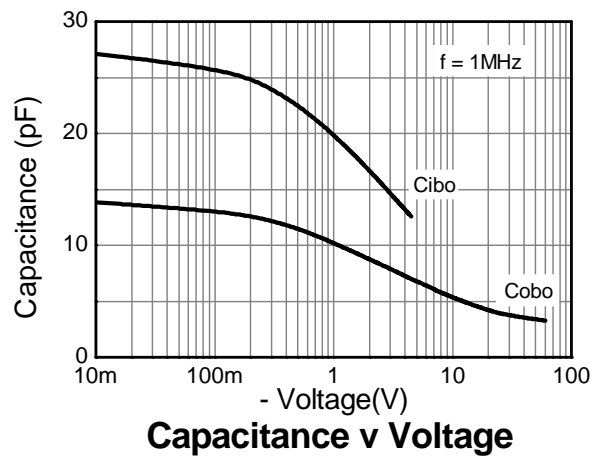
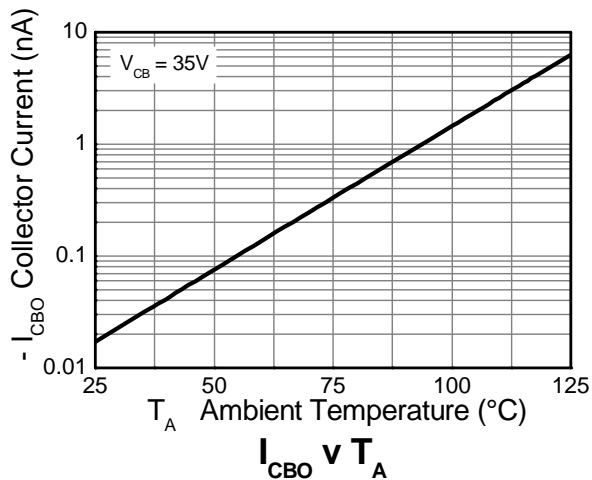
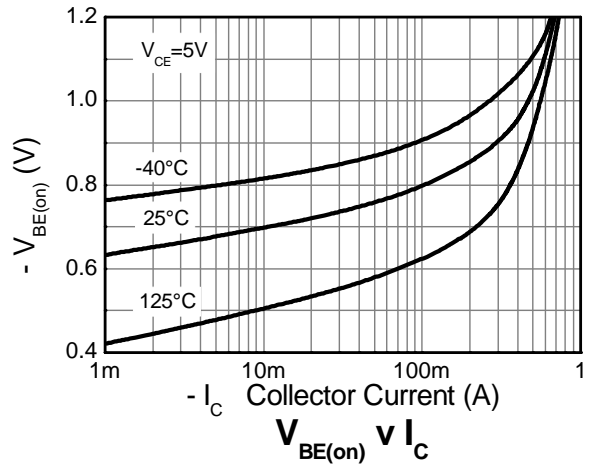
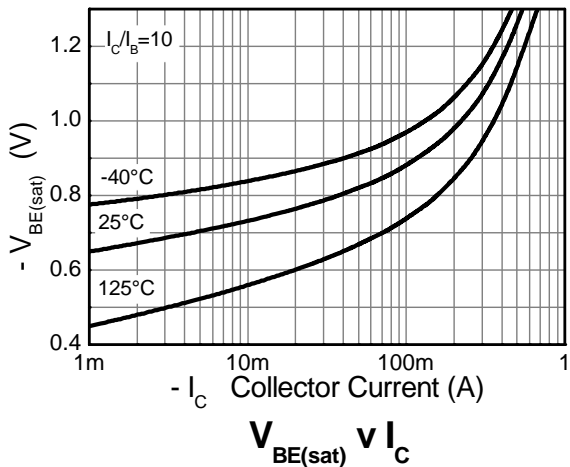
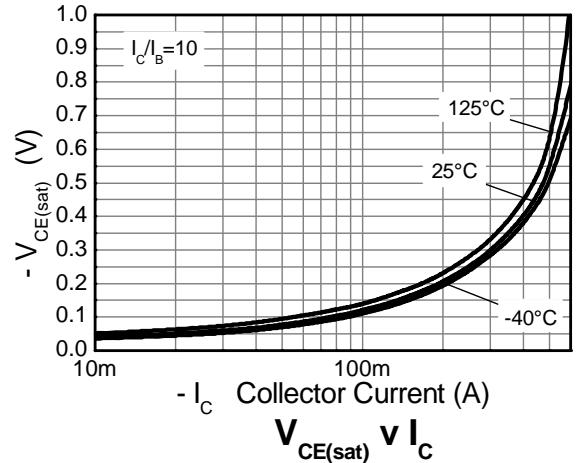
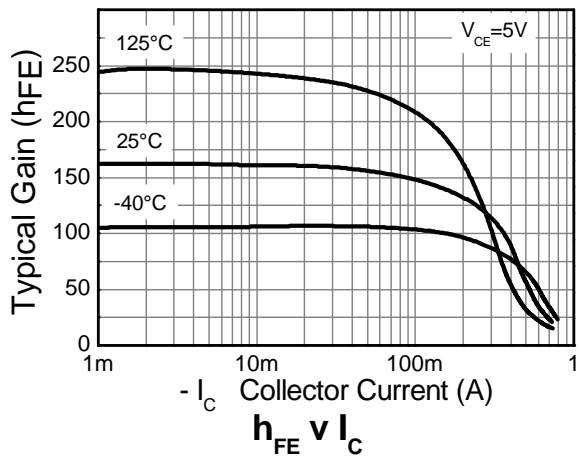


Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

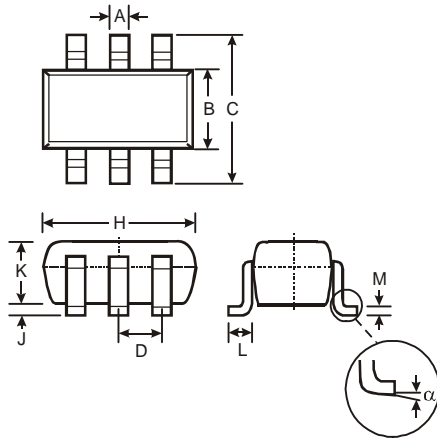
| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------|-----|------|----------|---------------|--|
| OFF CHARACTERISTICS | | | | | | |
| Collector-Base Breakdown Voltage | BV_{CBO} | -60 | — | — | V | $I_C = -10\mu\text{A}, I_E = 0$ |
| Collector-Emitter Breakdown Voltage (Note 8) | BV_{CEO} | -60 | — | — | V | $I_C = -10\text{mA}, I_B = 0$ |
| Emitter-Base Breakdown Voltage | BV_{EBO} | -5 | — | — | V | $I_E = -10\mu\text{A}, I_C = 0$ |
| Collector-Base Cutoff Current | I_{CBO} | — | — | -10 | nA | $V_{CB} = -50\text{V}, I_E = 0$ |
| | | — | — | -10 | μA | $V_{CB} = -50\text{V}, I_E = 0, T_A = 150^\circ\text{C}$ |
| Collector-Emitter Cutoff Current | I_{CEV} | — | — | ± 50 | nA | $V_{CE} = -30\text{V}, V_{BE} = \pm 0.25\text{V}$ |
| Base-Emitter Cutoff Current | I_{BEV} | — | — | ± 50 | nA | $V_{CE} = -30\text{V}, V_{BE} = \pm 0.25\text{V}$ |
| ON CHARACTERISTICS (Note 8) | | | | | | |
| DC Current Gain | h_{FE} | 75 | — | — | — | $I_C = -100\mu\text{A}, V_{CE} = -10\text{V}$ |
| | | 100 | — | — | | $I_C = -1.0\text{mA}, V_{CE} = -10\text{V}$ |
| | | 100 | — | — | | $I_C = -10\text{mA}, V_{CE} = -10\text{V}$ |
| | | 100 | — | 300 | | $I_C = -150\text{mA}, V_{CE} = -10\text{V}$ |
| | | 50 | — | — | | $I_C = -500\text{mA}, V_{CE} = -10\text{V}$ |
| Collector-Emitter Saturation Voltage | $V_{CE(sat)}$ | — | — | -0.4 | V | $I_C = -150\text{mA}, I_B = -15\text{mA}$ |
| | | — | — | -1.6 | | $I_C = -500\text{mA}, I_B = -50\text{mA}$ |
| Base-Emitter Saturation Voltage | $V_{BE(sat)}$ | — | — | -1.3 | V | $I_C = -150\text{mA}, I_B = -15\text{mA}$ |
| | | — | — | -2.6 | | $I_C = -500\text{mA}, I_B = -50\text{mA}$ |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Output Capacitance | C_{obo} | — | 5.2 | — | pF | $V_{CB} = -10\text{V}, f = 1.0\text{MHz}, I_E = 0\text{mA}$ |
| Input Capacitance | C_{ibo} | — | 16.3 | — | pF | $V_{EB} = -2.0\text{V}, f = 1.0\text{MHz}, I_C = 0\text{mA}$ |
| Current Gain-Bandwidth Product | f_T | 200 | 307 | — | MHz | $V_{CE} = -2\text{V}, I_C = -10\text{mA}, f = 100\text{MHz}$ |
| Turn-On Time | t_{on} | — | — | 21 | ns | $V_{CC} = -30\text{V}, I_C = -150\text{mA}, I_{B1} = -15\text{mA}$ |
| Delay Time | t_d | — | — | 5.5 | ns | |
| Rise Time | t_r | — | — | 15.3 | ns | |
| Turn-Off Time | t_{off} | — | — | 200 | ns | $V_{CC} = -6\text{V}, I_C = -150\text{mA}, I_{B1} = I_{B2} = -15\text{mA}$ |
| Storage Time | t_s | — | — | 160 | ns | |
| Fall Time | t_f | — | — | 40 | ns | |

 Notes: 8. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics

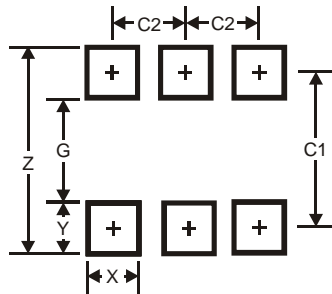


Package Outline Dimensions



| SOT26 | | | |
|----------------------|-------|------|------|
| Dim | Min | Max | Typ |
| A | 0.35 | 0.50 | 0.38 |
| B | 1.50 | 1.70 | 1.60 |
| C | 2.70 | 3.00 | 2.80 |
| D | — | — | 0.95 |
| H | 2.90 | 3.10 | 3.00 |
| J | 0.013 | 0.10 | 0.05 |
| K | 1.00 | 1.30 | 1.10 |
| L | 0.35 | 0.55 | 0.40 |
| M | 0.10 | 0.20 | 0.15 |
| α | 0° | 8° | — |
| All Dimensions in mm | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 3.20 |
| G | 1.60 |
| X | 0.55 |
| Y | 0.80 |
| C1 | 2.40 |
| C2 | 0.95 |

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